

| L Number | Hits | Search Text | DB | Time stamp |
|----------|--------|---|------------------------------------|------------------|
| 1 | 7875 | residue\$ near5 (measur\$4 or detect\$4 or inspect\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 14:47 |
| 2 | 3411 | chemical near3 mechanical near planarization | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 14:47 |
| 3 | 5166 | chemical near3 mechanical near3 planarization | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 14:48 |
| 4 | 18 | (residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (chemical near3 mechanical near3 planarization) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:03 |
| 5 | 4 | 6137570.URPN. | USPAT | 2003/06/10 14:52 |
| 6 | 383107 | light near3 source | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:03 |
| 7 | 868708 | detector\$ | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:03 |
| 8 | 223 | (residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$ | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:04 |
| 9 | 32071 | spectrophotometer | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:04 |
| 10 | 25 | ((residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$) and spectrophotometer | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:46 |
| 11 | 223 | (residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$ | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:46 |
| 12 | 74755 | 356/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:46 |
| 13 | 36 | ((residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$) and 356/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:47 |
| 14 | 34 | ((residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$) and 356/\$.ccls.) not (((residue\$ near5 (measur\$4 or detect\$4 or inspect\$4)) and (light near3 source) and detector\$) and spectrophotometer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/10 15:47 |

US-PAT-NO: 6137570

DOCUMENT-IDENTIFIER: US 6137570 A

TITLE: System and method for
analyzing topological features on
a surface

----- KWIC -----

Brief Summary Text - BSTX (5):

These and similar problems often arise when processing equipment malfunctions or degrades in performance over time. Examples of such equipment include plasma etchers, deposition systems, chemical mechanical planarization systems, reticle processing, and photolithography equipment. Obviously, a manufacturer needs to know when the process equipment ceases to function in an acceptable manner.

Detailed Description Text - DETX (8):

For the case of an opening in a surface or surface film, this invention may evaluate various parameters characterizing such openings. For example, the invention may detect variations in opening diameter, depth, and angle. Thus, it may detect whether a via or contact is

over etched, under etched, too wide, too narrow, too conical, angled too far from the surface normal, etc. It may also detect the presence of residue left in such openings.